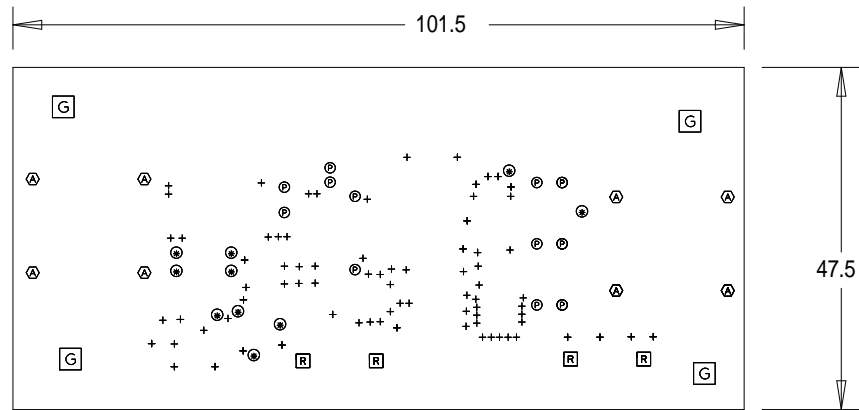



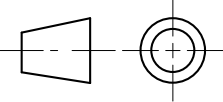
SPEC:

COMPLIANT RoHS DIRECTIVE 2011/65/UE

MATERIAL	FR4 IMPROVED (low CTE)		
BOARD THICKNESS		1.6mm /63mils	
STACKUP	MC4/4LAYERS		
MINIMAL GAP		200um /8.0mils	
MINIMAL SLIVER		200um /8.0mils	
COPPER THICKNESS		35um(1oz)at START	
FINISH THICKNESS	CHEMICAL NiAu		
SOLDER MASK		GREEN TOP & BOT	
SILKSCREEN	WHITE TOP & BOT		
ALL BOARD ELECTRICALLY TESTED			
MANUFACTURE 'S LOGO & DATECODE MARKED ON BOTTOM SOLDERMASK			



DRILL CHART: TOP to BOTTOM					
ALL UNITS ARE IN MILLIMETERS					
FIGURE	SIZE		TOLERANCE	PLATED	QTY
+	0.5	VIA	+0.0/-0.0	PLATED	79
@	0.8		+0.1/-0.05	PLATED	12
⊙	1.0		+0.1/-0.05	PLATED	10
R	1.2		+0.1/-0.05	PLATED	4
⊗	1.8		+0.1/-0.05	PLATED	8
G	3.0		+0.1/-0.1	NON-PLATED	4

3.0			w21/2021	
2.0			w42/2020	
1.0			w45/2019	
indice	Description	Date		
Controle par :		Autorise par:		
 ON semiconductor	Definition CUT DRILL DRAWING PLAN PRECAGE DETOURAGE			
	Subc.	DYPE TECH	Dessine: e B	
Board: NCx1271x-SSR12V-C		Echelle: 1/1		
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